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(54) **Title:** VERSATILE DUAL-LAYER TEMPORARY WAFER BONDING FOR HARSH PROCESSING CONDITIONS

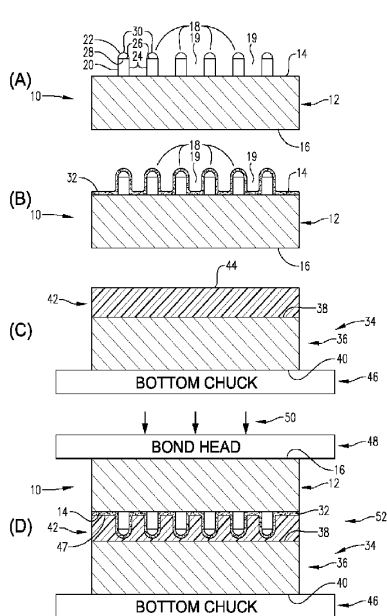


Fig. 1

(57) **Abstract:** A dual-layer temporary bonding system for semiconductor manufacturing including first and second bonding layers is provided. The first bonding layer includes a bond line adhesion promoter that acts as a bond line adhesion promoter during the bonding process. The second bonding layer includes one or more functionalities that will react with the bond line adhesion promoter during the bonding process. The materials and methods of this system can provide increased, precisely controlled, bond line adhesion while at the same time also satisfying other desired performance criteria.